

ABSTRACT OF THE DISCLOSURE

The invention provides an electronic assembly comprising a carrier substrate, a die, and a solidified underfill material. The carrier substrate has an upper plane. The die has a die substrate and an integrated circuit formed on one side of the die substrate. The die has a lower major surface over the upper plane, an upper major surface, and a plurality of side edge surfaces from the upper major surface to the lower major surface. A corner edge portion where extensions of two of the side edge surfaces meet has been removed. The solidified underfill material is located between and contacts both the upper plane of the carrier substrate and the lower surface of the die.